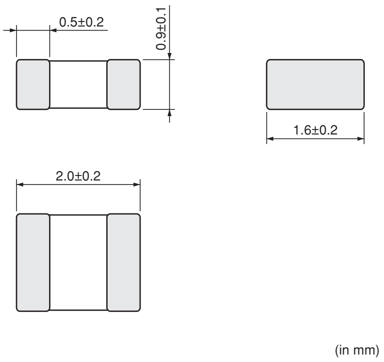
EMIFIL® (Inductor type) ChipEMIFIL®

NFZ2MSM_SN10 Series (0806 Size)

■ Dimensions



■ Equivalent Circuit

(Resistance element becomes dominant at high frequencies.)

■ Packaging

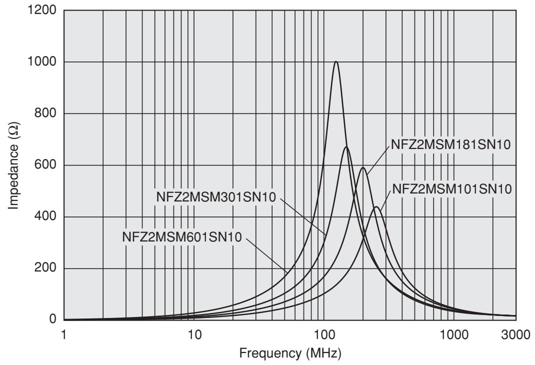
Code	Packaging	Minimum Quantity
L	180mm Embossed Tape	3000
B	Bulk(Bag)	1000

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1MHz/20°C)	Rated Current	DC Resistance	Operating Temperature Range (Self-temperature rise is included)	Operating Temperature Range
NFZ2MSM101SN10□	100ohm ±25%	-	4000mA	0.014ohm (Typ.)	-	-40 to +85°C
NFZ2MSM181SN10□	180ohm ±25%	-	3400mA	0.020ohm (Typ.)	-	-40 to +85°C
NFZ2MSM301SN10□	300ohm ±25%	-	3100mA	0.024ohm (Typ.)	-	-40 to +85°C
NFZ2MSM601SN10□	600ohm ±25%	-	2500mA	0.037ohm (Typ.)	-	-40 to +85°C

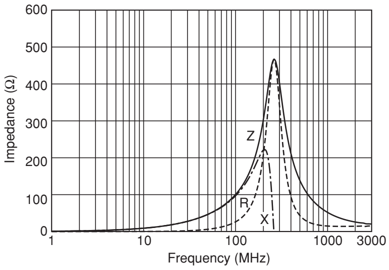
Number of Circuits: 1

■ Impedance-Frequency Characteristics (Main Items)



■ Impedance-Frequency Characteristics

NFZ2MSM101SN10



Continued on the following page. ↗

●This data sheet is applied for CHIP EMIFIL® used for General Electronics equipment for your design.

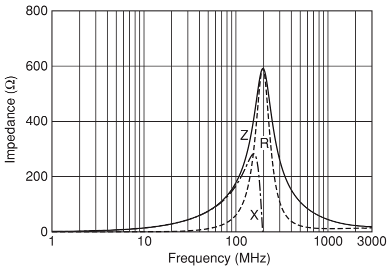
⚠Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it’s specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

↘ Continued from the preceding page.

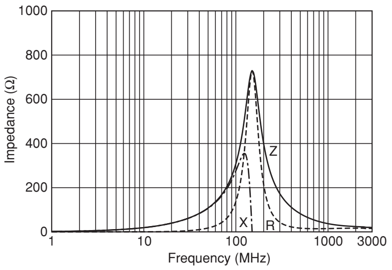
■ Impedance-Frequency Characteristics

NFZ2MSM181SN10



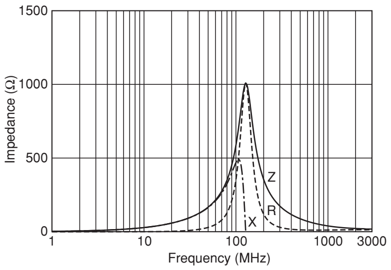
■ Impedance-Frequency Characteristics

NFZ2MSM301SN10



■ Impedance-Frequency Characteristics

NFZ2MSM601SN10



■ ⚠Caution/Notice

⚠Caution (Rating)

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.